

General Description

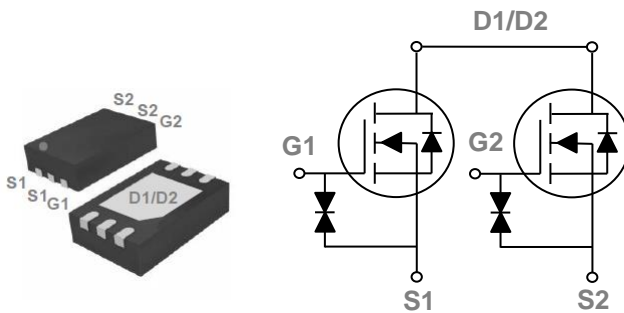
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

| | | |
|-------|-------|-----|
| BVDSS | RDSON | ID |
| 20V | 5.9mΩ | 30A |

Features

- 20V,30A, $R_{DS(ON)} = 5.9m\Omega$ @ $V_{GS} = 4.5V$
- Improved dv/dt capability
- Fast switching
- G-S ESD Protection Diode Embedded
- Green Device Available

DFN2x3 Dual Pin Configuration



Applications

- Handheld Instruments
- POL Applications
- Battery Protection Applications

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|--|------------|---------------|
| V_{DS} | Drain-Source Voltage | 20 | V |
| V_{GS} | Gate-Source Voltage | ± 12 | V |
| I_D | Drain Current – Continuous ($T_A=25^\circ C$) | 11.5 | A |
| | Drain Current – Continuous ($T_A=70^\circ C$) | 9 | A |
| | Drain Current – Continuous ($T_C=25^\circ C$) | 30 | A |
| | Drain Current – Continuous ($T_C=100^\circ C$) | 19 | A |
| I_{DM} | Drain Current – Pulsed ¹ ($T_C=25^\circ C$) | 120 | A |
| P_D | Power Dissipation ($T_A=25^\circ C$) | 1.56 | W |
| | Power Dissipation – Derate above $25^\circ C$ | 0.013 | W/ $^\circ C$ |
| | Power Dissipation ($T_C=25^\circ C$) | 10.2 | W |
| | Power Dissipation – Derate above $25^\circ C$ | 0.081 | W/ $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 80 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | --- | 12.3 | $^\circ C/W$ |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------|--------------------------------|---|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 20 | --- | --- | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =18V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | μA |
| | | V _{DS} =16V, V _{GS} =0V, T _J =70°C | --- | --- | 10 | μA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±12V, V _{DS} =0V | --- | --- | ±10 | μA |

On Characteristics

| | | | | | | |
|---------------------|-----------------------------------|--|-----|------|-----|----|
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =4.5V, I _D =5.5A | 4.0 | 5.0 | 5.9 | mΩ |
| | | V _{GS} =4.0V, I _D =5.5A | 4.1 | 5.1 | 6.3 | mΩ |
| | | V _{GS} =3.8V, I _D =5.5A | 4.2 | 5.3 | 6.6 | mΩ |
| | | V _{GS} =3.1V, I _D =5.5A | 4.3 | 5.6 | 7.1 | mΩ |
| | | V _{GS} =2.5V, I _D =5.5A | 4.9 | 6.7 | 8.7 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250μA | 0.5 | 0.75 | 1.5 | V |

Dynamic and switching Characteristics²

| | | | | | | |
|---------------------|------------------------------|--|-----|-----|-----|----|
| Q _g | Total Gate Charge | V _{DS} =10V, V _{GS} =4.5V, I _D =15A | --- | 19 | 30 | nC |
| Q _{gs} | Gate-Source Charge | | --- | 1.6 | 5 | |
| Q _{gd} | Gate-Drain Charge | | --- | 4.8 | 10 | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =10V, V _{GS} =4.5V, R _G =6Ω I _D =15A | --- | 30 | 50 | ns |
| T _r | Rise Time | | --- | 70 | 100 | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 80 | 120 | |
| T _f | Fall Time | | --- | 105 | 160 | |
| C _{iss} | Input Capacitance | V _{DS} =10V, V _{GS} =0V, F=1MHz | --- | 440 | 660 | pF |
| C _{oss} | Output Capacitance | | --- | 220 | 350 | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 56 | 90 | |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|---------------------------|---|------|------|------|------|
| I _S | Continuous Source Current | V _G =V _D =0V, Force Current | --- | --- | 30 | A |
| I _{SM} | Pulsed Source Current | | --- | --- | 60 | A |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V, I _S =1A, T _J =25°C | --- | --- | 1 | V |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. Essentially independent of operating temperature.

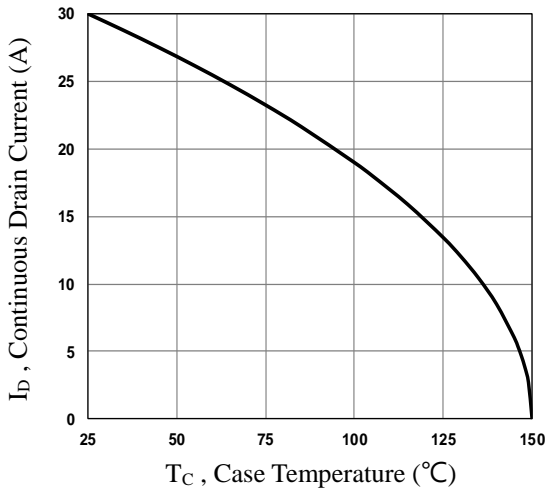


Fig.1 Continuous Drain Current vs. T_c

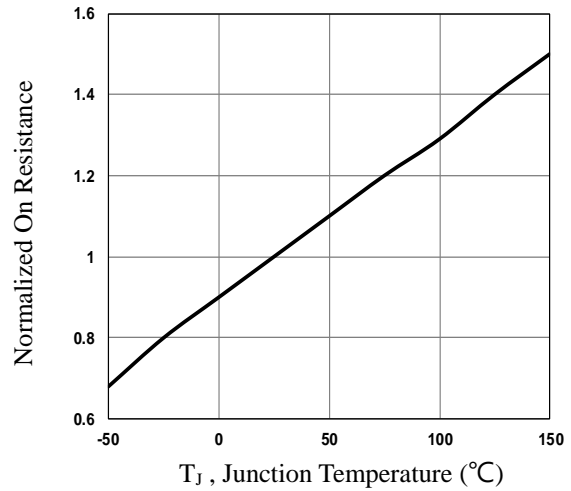


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

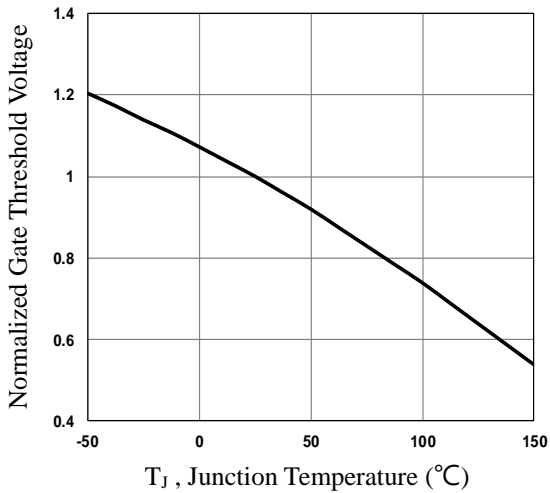


Fig.3 Normalized V_{th} vs. T_j

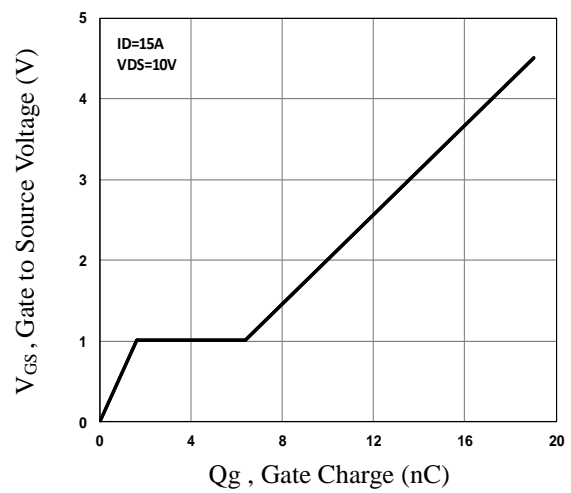


Fig.4 Gate Charge Waveform

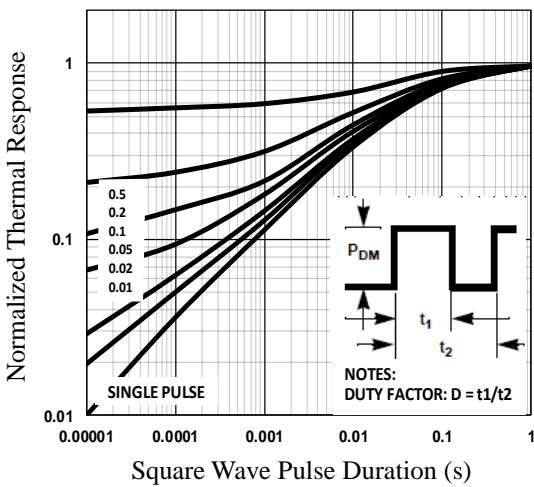


Fig.5 Normalized Transient Response

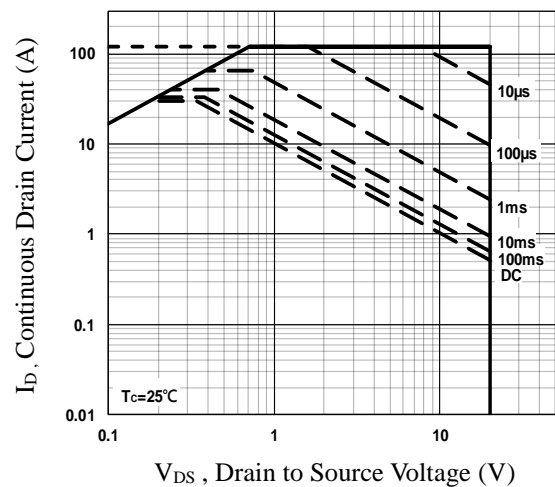


Fig.6 Maximum Safe Operation Area

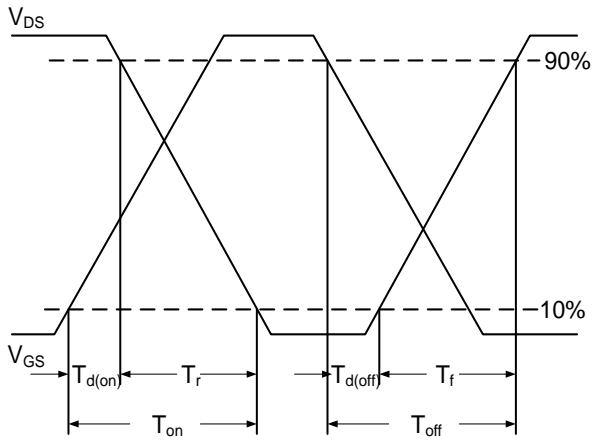


Fig.7 Switching Time Waveform

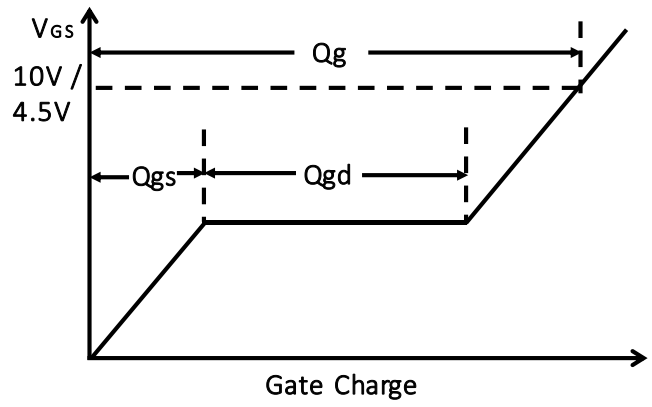
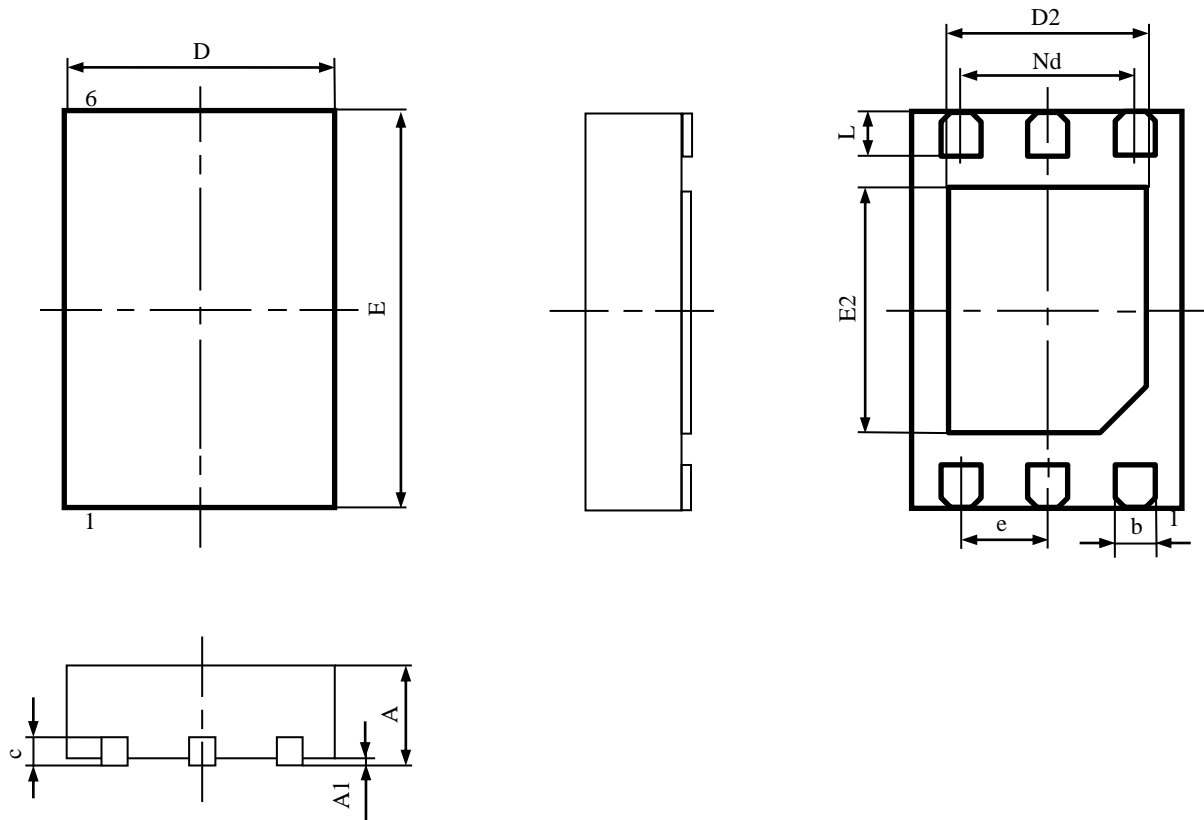


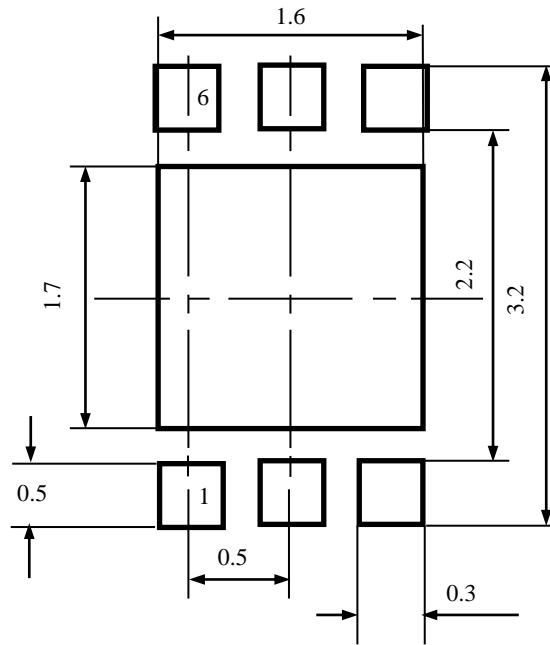
Fig.8 Gate Charge Waveform

DFN2X3 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|----------|----------------------|-----------|
| | MAX | MIN | MAX | MIN |
| A | 0.800 | 0.700 | 0.031 | 0.028 |
| A1 | 0.050 | 0.02typ. | 0.002 | 0.001typ. |
| b | 0.350 | 0.200 | 0.014 | 0.008 |
| c | 0.250 | 0.180 | 0.010 | 0.007 |
| D | 2.100 | 1.900 | 0.083 | 0.075 |
| D2 | 1.600 | 1.400 | 0.063 | 0.055 |
| e | 0.5BSC | | 0.02BSC | |
| Nd | 1.0BSC | | 0.04BSC | |
| E | 3.100 | 2.900 | 0.122 | 0.114 |
| E2 | 1.750 | 1.650 | 0.069 | 0.065 |
| L | 0.400 | 0.300 | 0.016 | 0.012 |

DFN2X3 RECOMMENDED LAND PATTERN



unit : mm